X-23-8033-1

Shin-Etsu Silicones of America, Inc.
800-544-1745

Product Description

Shin-Etsu's X-23-8033-1 thermal interface grease is a solvent-diluted grease that exhibits superior thermal conductivity after the added solvent has evaporated. Due to the dilution of X-23-8033-1, it is easy to work with, while still maintaining excellent thermal conductivity.

Product Features

- Superior thermal conductivity
- Solvent diluted
- Ease of use

Typical Applications

- CPUs
- MPUs
- Semiconductor elements and heat sinks requiring high thermal conductivity

Typical Properties

Type	Thermal Grease
One/Two Component	One
Low Molecular Weight Siloxane Stripped?	Y
Color	White
Density @ 23C (g/cm^3)	3.48
Viscosity (Pa·s)	70
Dielectric Strength (kV/mm)	10.0
Thermal Conductivity (W/m·K)	4.00
Thermal Resistance (mm2·K/W)	10
% Volatile Content	0.93
Usable Temp. Range (C)	-40 to +200
Bond Line Thickness (µm)	32

Note: Values are not for specification purposes.

Warranty- The information and data contained herein are believed to be accurate and reliable; however it is the user's responsibility to determine suitability of use. Since Shin-Etsu Silicones, Inc. cannot know all of the uses to which its products may be put or the conditions of use, it makes no warranties concerning the fitness or suitability of its products for a particular use or purpose. You should thoroughly test any proposed use of our products and independently conclude satisfactory performance in your application. Likewise, if the manner in which our products are used requires governmental approval or clearance, you must obtain it. Shin-Etsu Silicones, Inc. warrants only that its products will meet its specifications. There is no warranty of merchantability of fitness of use, nor any other expressed or implied warranties. The user's exclusive remedy and Shin-Etsu Silicones, Inc.'s sole liability is limited to refund of the price or replacement of any product shown to be otherwise than as warranted. Shin-Etsu Silicones, Inc. will not be liable for incidental or consequential damages of any kind. Suggestions of uses should not be taken as inducements to infringe any patents.